

L Number	Hits	Search Text	DB	Time stamp
21	48	4631416.URPN.	USPAT	2004/04/28 18:27
58	5	5182455.URPN.	USPAT	2004/04/28 18:44
59	15942	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.)	USPAT; US-PGPUB	2004/04/28 18:46
60	762	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT	2004/04/28 18:47
61	288	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT	2004/04/28 18:47
62	48	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT	2004/04/28 18:48
63	1043	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 19:15
64	353	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 18:47
65	60	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 19:15
66	374	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	EPO; JPO; DERWENT; IBM_TDB	2004/04/28 19:10
67	13	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	EPO; JPO; DERWENT; IBM_TDB	2004/04/28 19:03
68	23	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	EPO; JPO; DERWENT; IBM_TDB	2004/04/28 19:11
69	1	2003-492470.NRAN.	DERWENT	2004/04/28 19:14
70	88	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 19:15
71	436	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 19:15
72	155	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 19:16
73	237	((356/399,400,401,388,614).CCLS.) ((250/492.2,491.1,548,559.29,559.3,559.36).CCLS.) ((355/53,55,67,77).CCLS.) ((430/22,30,5).CCLS.) ((382/151).CCLS.) ((438/401).CCLS.)) and ((align\$ near (spot beam)) same (wafer semiconduct\$ semiconduct\$ substrate))	USPAT; US-PGPUB	2004/04/28 19:16